VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

The paragraph beginning on page 1, line 4 has been amended as indicated.

--This application is related to [copending U.S. patent application, Serial No. 09/457,776, filed December 9, 1999 and copending] U.S. Patent No. 6,264,476, issued to Li et al. for WIRE SEGMENT BASED INTERPOSER FOR HIGH FREQUENCY ELECTRICAL CONNECTION, which is based on application Serial No. 09/457,776, filed December 9, 1999 and U.S. Patent No. 6,312,266, issued to Fan et al. for CARRIER FOR LAND GRID ARRAY CONNECTORS, which is based on U.S. patent application Serial No. 09/645,860, filed August 24, 2000, both of which are hereby incorporated by reference.--

IN THE ABSTRACT:

The abstract has been amended as indicated.

--[The present invention features an] An interposer [that] provides a high reliability interface between an LGA connector and a motherboard. The [novel interposer overcomes the limitations of prior art interposers by including]

interposer includes a stepped spacer for each solder interconnection which prevents the relaxation of mechanical contact force while ensuring the integrity of each solder interconnection. The interposer provides noble metal plated contact pads on a first surface to receive the contact members of an LGA connector, and contact pads for BGA solder connections for attachment to a motherboard. A description of the processes to manufacture the interposer is also disclosed.--

IN THE CLAIMS:

Claim 1 has been amended as indicated.

1. (Amended) A low cost, high reliability interposer for use in electronic packages, comprising:

a) at least one dielectric layer having one major surface and at least one edge;

b) a plurality of conductive pads, each having a first and second surface, spaced apart on said major surface of said at least one dielectric layer, said first surface of said conductive pads being plated with at least one layer of metal, and at least a portion of said second surface of said conductive

pads being readily adaptable for connection to a conductive member;

c) a plurality of openings disposed in the interposer, said openings having [with] a non-uniform cross section, each [one] opening corresponding to and aligned with one of said conductive pads; and

d) a plurality of reformable conductive members, each one located within one of said openings of said interposer and in electrical contact with said portion of said second surface of said conductive pads.